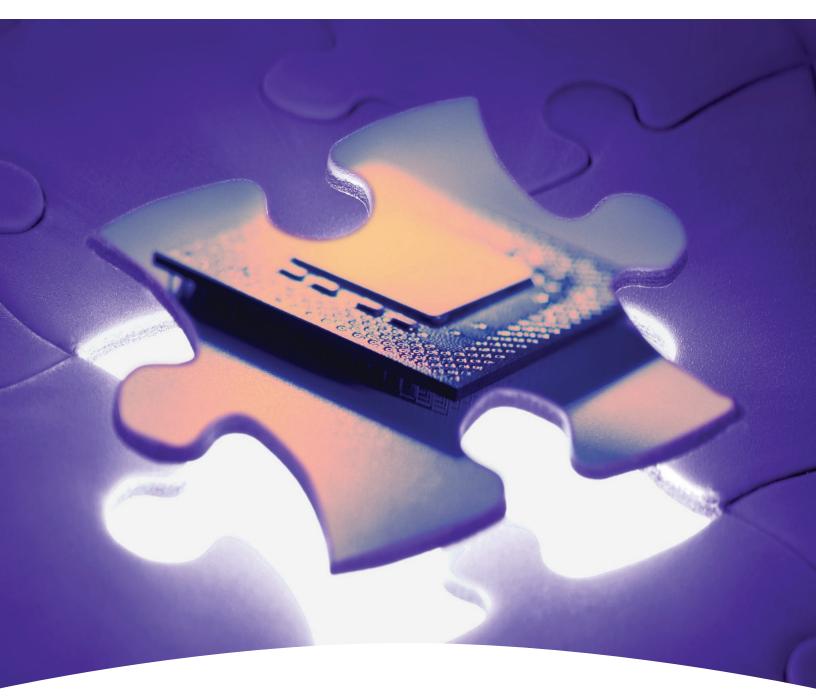
# **Packaging Materials**

# **Honeywell**



Honeywell PTM3180
Phase Change Thermal
Interface Material

# Honeywell PTM3180 Phase **Change Thermal Interface Material**

HIGHLY THERMALLY CONDUC-TIVE PHASE CHANGE MATERIAL IN PAD AND DISPENSE FORMATS

#### **BENEFITS**

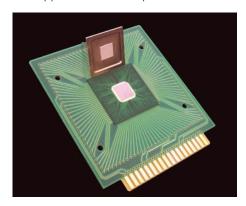
- High performance filler and polymer technology
- Phase change at 45°C
- · Highly conductive filler with tailored loading to optimize performance
- Superior handling and reworkability
- Reliable thermal performance

#### **FEATURES**

• Key outputs in thermal impedance for PTM3180 have been measured to fit individual needs.

#### **OVERVIEW**

Honeywell PTM3180, a highly thermally conductive Phase Change Material (PCM) in both pad and dispense formats, is designed to minimize thermal resistance at interfaces, maintain excellent performance through reliability testing, and provide scalable application at a competitive cost.



Based on a novel polymer PCM system, this material exhibits excellent wetting at interfaces during typical operating temperature ranges, resulting in very low surface contact resistance.

A proprietary filler material provides high thermal conductivity (4.4 W/m·K) and low thermal impedance (<0.16°Ccm<sup>2</sup>/W @ 2 mil), making PTM3180 desirable for high performance integrated circuit devices.

### **APPLICATIONS**

Clamping pressure and temperature are suggested to achieve a minimum bond line thickness of the thermal interface material, typically less than 1.5 mil (0.038mm) for best performance. The material must go through the phase change temperature in order to exhibit entitlement performance.

## Roll Format Tape:

- Plastic liner
- 10 mil (0.25mm) thickness supplied



# PTM3180 Thermal Impedance **ASTM D-5470** 0.35 Thermal Impedance ( °C-cm²/W 0.30 0.25 PTM3180 k = 4.4 W/m-K 0.20 0.15 0.10 0.05 0.00 20 100 120 140 Bond Line Thickness (µm)

#### **Physical Properties**

Thermal Conductivity Thermal Impedance @ 50µm @~20µm

Volume Resistivity Specific Gravity Typical Bond Line Thickness (No Shim @ 40 PSI)

4.4 W/m-K 0.14°C-cm2/W 0.06°C-cm2/W  $3.0 \times 10^{15} \Omega$ -cm 2.3 g/cm<sup>3</sup> 0.6 mil

## Storage & Use

Shelf Life

1 Year at 25°C

#### Thermal Impedance Post Reliability

0.10°C-cm2/W End of Line Temperature Cycling "B" 0.07°C-cm2/W (-55°C to 125°C, 1000 cycles) 0.08°C-cm2/W Bake 125°C, 1000 h

Bake 150°C, 1000 h 0.07°C-cm2/W 0.09°C-cm2/W HAST, 96 h 0.11°C-cm2/W 85°C, 85% RH, 1000 h



#### **Honeywell Electronic Materials**

USA: 1-509-252-2102 China: 86-21-28942481 Germany: 49-5137-999-9199 Japan: 81-3-6730-7092 Korea: 82-2-3483-5076 Singapore: 65-6580-3593 Taiwan: 886-3-6580300 ext.312

www.honeywell.com/sm/em

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